Chip Card & Security ICs

my-d® vicinity

SRF 55V02P

Intelligent 2.5 Kbit EEPROM
with Contactless Interface compliant to ISO/IEC 15693
and ISO/IEC 18000-3 mode 1

Plain Mode Operation

Short Product Information   July 2007

Revision History:	**Current Version 2007-07-02**
Previous Releases:	2002-07-30
Page	Subjects (changes since last revision)
	Editorial changes

Important:	For further information please contact: Infineon Technologies AG in Munich, Germany, Chip Card & Security ICs, Fax +49 (0)89 / 234-955 9372 E-Mail: security.chipcard.ics@infineon.com

To our valued customers

We constantly strive to improve the quality of all our products and documentation. We have spent an exceptional amount of time to ensure that this document is correct. However, we realise that we may have missed a few things. If you find any information that is missing or appears in error, please use the contact section above to inform us. We appreciate your assistance in making this a better document.

Attention please!

The information herein is given to describe certain components and shall not be considered as warranted characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Infineon Technologies is an approved CECC manufacturer.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office in Germany or our Infineon Technologies Representatives world-wide (see address list).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Intelligent 2.5 Kbit EEPROM
with Contactless Interface (ISO/IEC 15693 and ISO/IEC 18000-3 mode 1)

Features

Contactless Interface

- Physical Interface and Anticollision compliant to ISO/IEC 15693 and ISO/IEC 18000-3 mode 1
  — contactless transmission of data and supply energy
  — carrier frequency: 13.56 MHz
  — data rate up to 26 kbit/s
  — anticollision with identification of up to 30 tags/sec
  — read / write distance up to 150 cm depending on reader antenna configuration

2.5 Kbit EEPROM

- ISO mode – block organization of memory
  — up to 56 blocks of user memory (block size 4 bytes)
- Custom mode – page organization of memory
  — up to 32 pages of user memory (page size 8 bytes)
- Unique chip identification number (UID)
- EEPROM programming time per block/page < 4 ms
- EEPROM endurance > 100,000 erase/write cycles[1]
- Data retention > 10 years[1]

Value Counters: up to 65536 (value range from 0 to $2^{16}-1$)
  — each page in the User Area is configurable as a Value Counter
  — support of Anti-Tearing

Electrical characteristics

- ESD protection minimum 2 kV
- Ambient temperature –25 … +70°C (for the chip)

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[1] Values are temperature dependent

Development Tool

— my-d® Evaluation Kit including my-d® Manager Software

1 Ordering and Packaging information

Table 1: Ordering Information

Type	Package[1]	Memory User	Admin.	Pages	Ordering Code
SRF 55V02P C	Sawn wafer				SP000009363
SRF 55V02P NB	NiAu bump wafer	256 bytes	64 bytes	32	SP000089856
SRF 55V02P MFCC1	S-MFCC1-2-1				SP000010033
SRF 55V02P MCC2	P-MCC2-2-1				SP000009367

For more ordering information (wafer thickness and height of NiAu-Bump) please contact your local Infineon sales office.
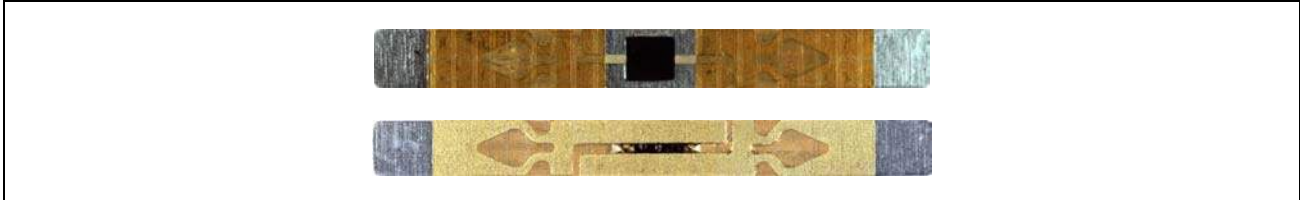
Pin Description

Figure 1: Pin Configuration Module Contactless Card – MFCC1 (top / bottom view)

Figure 2: Pin Configuration Module Contactless Card – MCC2 (top view)

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[1] Available as a Module Flip Chip Contactless (MFCC1), Module Contactless Card (MCC) for embedding in plastic cards, as NiAu-bump version (NB) or as a die on sawn / unsawn wafer for customer packaging
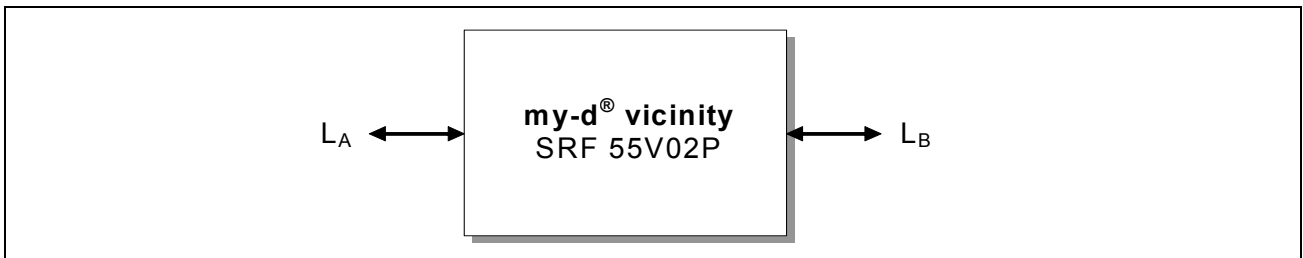
Figure 3: Pad Configuration Die

Table 2   Pin Definitions and Functions

Symbol	Function
L_A	Antenna connection
L_B	Antenna connection

2   my-d® product family

The my-d® products are designed to meet increased demands for security and design flexibility. The family of contactless memory my-d® supplies the user with different memory sizes and incorporates security features to enable considerable flexibility in the application design.

The functional architecture, meaning the memory organisation and authentication of my-d® products is the same for both, my-d® proximity (ISO/IEC 14443) and my-d® vicinity (ISO/IEC 18000-3 mode 1 or ISO/IEC 15693). This eases the system design and allows simple adaptation between applications.

All my-d® products are available in plain mode with open memory access and in secure mode with memory access controlled by authentication procedures.

Flexible controls within the my-d ICs start with plain mode operation and individual page locking for more complex applications various settings in secure mode can be set for multi user / multi application configurations.

In secure mode a cryptographic algorithm based on 64-bit key is available. Mutual authentication, message authentication codes (MAC) and customized access conditions protect the memory against unauthorized access. Configurable value counters featuring anti-tearing functionality are suitable for value token applications, such as limited use transportation tickets.

Architectural interoperability of all my-d® products enables an easy migration from simple to more demanding applications.

In addition, the my-d® light (ISO/IEC 18000-3 mode 1 or ISO/IEC 15693) is part of the my-d® family. Its optimized command set and memory expands the range of applications to cost sensitive segments.

3   SRF 55V02P my-d® vicinity plain

All my-d® vicinity products comply with ISO/IEC 18000-3 mode 1 or ISO/IEC 15693 standards for contactless vicinity smart cards. The power supply and data are transferred to the my-d® products via an antenna. The my-d® vicinity is designed to communicate within the operating distance of up to 1.5m depending on appropriate reader antenna configurations.

3.1   Circuit Description

The my-d® vicinity is made up of an EEPROM memory unit, an analog interface for contactless energy and data transmission and a control unit.
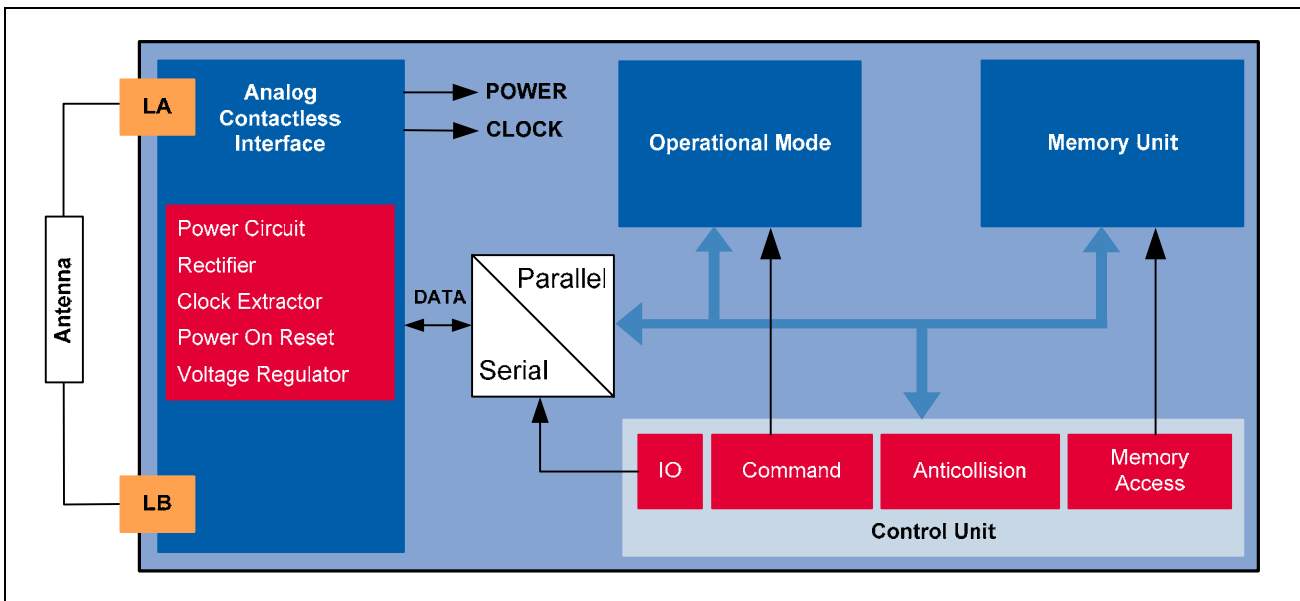

Figure 4:   Block diagram of the my-d® vicinity plain

- **Analog Contactless Interface:**
  The Analog Contactless Interface comprises the voltage rectifier, voltage regulator and system clock to supply the IC with appropriate power. Additionally the data stream is modulated and demodulated.

- **Operational mode**
  The access to the memory depends on the actual mode of the my-d® vicinity. The memory is accessed according to plain or secure mode after the VICC is selected.

- **Memory Unit**
  The Memory Unit consists of 320 bytes organised in 32 pages each of 8 user and 2 administration bytes.

- **Control Unit**
  The Control Unit decodes and executes all commands. Additionally the control unit is responsible for the correct anticollision flow.

3.2 Memory Principle

The User Memory is built up with up to 56 blocks of 4 bytes each. Individual block locking allows the user to protect the stored data.

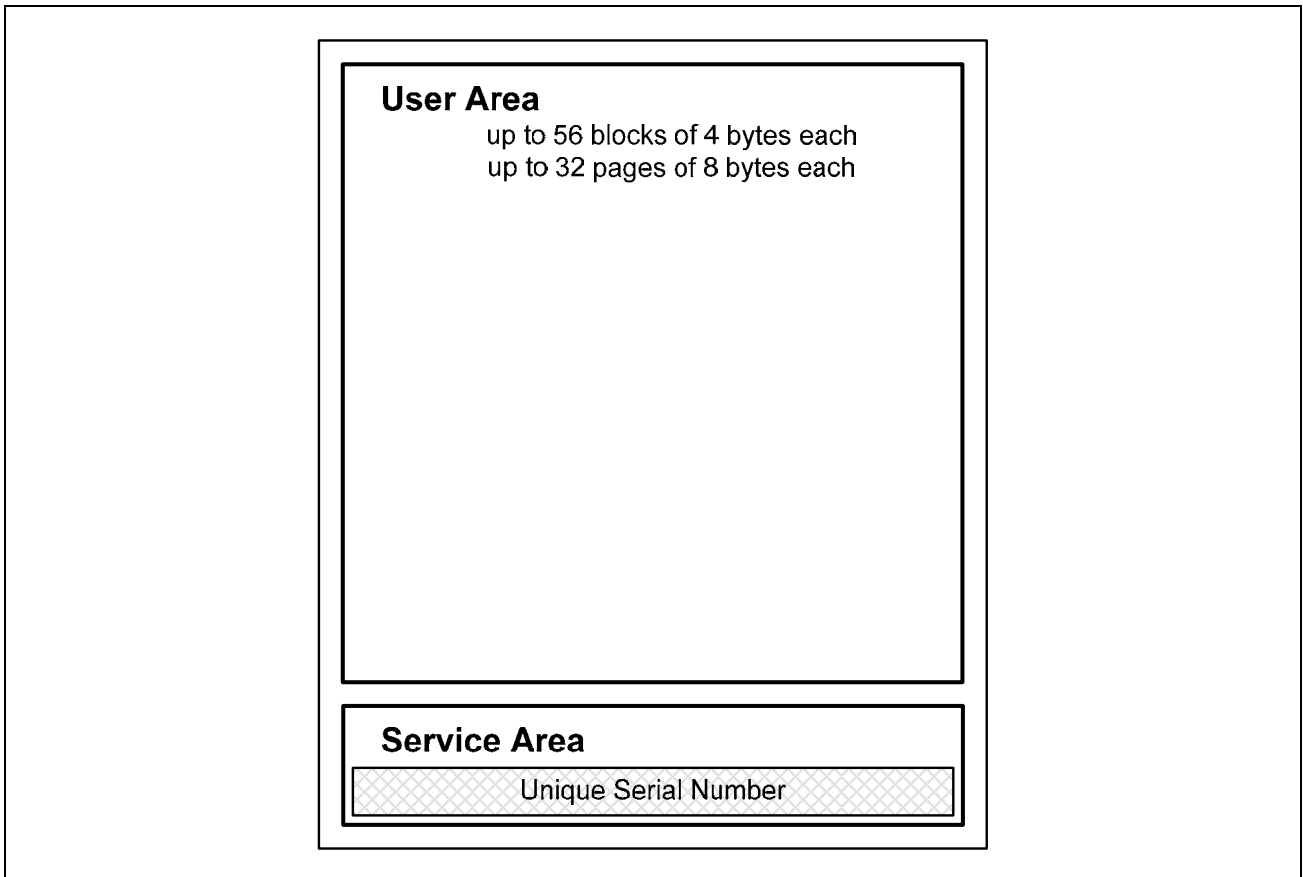The service area contains the UID and manufacturer data. The service area cannot be changed.

User Area
up to 56 blocks of 4 bytes each
up to 32 pages of 8 bytes each

Service Area
Unique Serial Number

Figure 5: Memory principle of my-d® SRF 55V02P

3.3   System Overview

The system consists of a contactless label and a contactless reader together with an antenna. The transponder is powered by the high frequency field generated by the VCD (Vicinity Coupling Device).
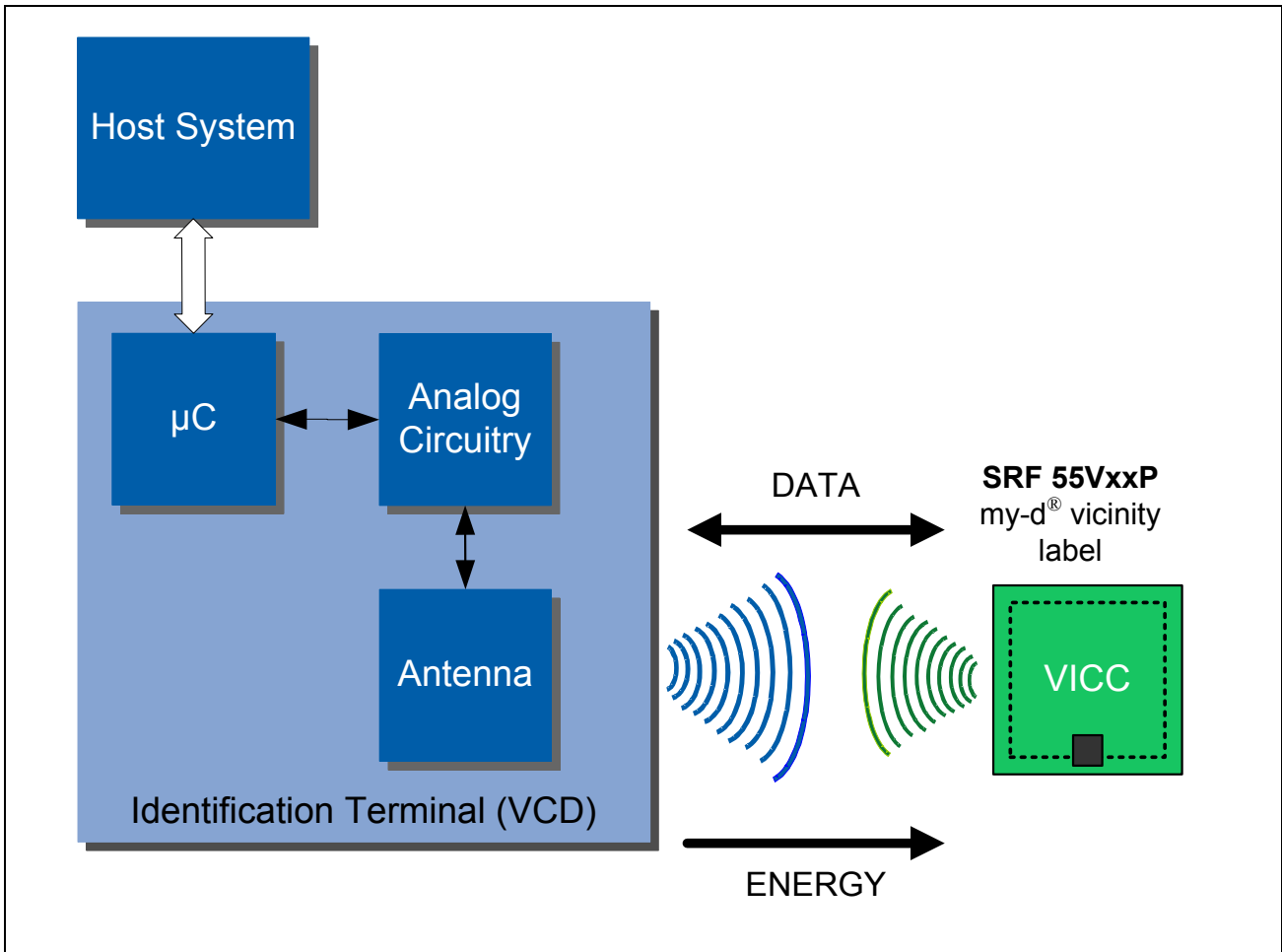

Figure 6:   Contactless System Example my-d® vicinity plain

- VICC – Vicinity Card according to ISO/IEC 18000-3 mode 1 or ISO/IEC 15693

Contactless Energy and Data Transfer

The read / write distance is up to 1.5 m depending on an appropriate reader antenna configuration. The label antenna consists of a simple coil with few turns. Contactless labels are passive. The RF communication interface exchanges data with data rates of up to 26 kbit/s.
An intelligent anticollision function enables operation of more than one label in the field simultaneously. The anticollision algorithm selects each label individually and ensures that the execution of a transaction with a selected label is performed correctly without data corruption resulting from other labels.